

Title (en)

ELECTRONIC MODULE, PANEL WITH INDIVIDUAL ELECTRONIC MODULES AND METHOD FOR THE PRODUCTION THEREOF

Title (de)

ELEKTRONISCHES MODUL, NUTZEN MIT ZU VEREINZELNDEN ELEKTRONISCHEN MODULEN UND VERFAHREN ZU DEREN HERSTELLUNG

Title (fr)

MODULE ELECTRONIQUE, TABLEAU MUNI DE MODULES ELECTRONIQUES A SEPARER ET PROCEDE DE PRODUCTION CORRESPONDANT

Publication

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Application

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Priority

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Abstract (en)

[origin: WO03075347A2] The invention relates to an electronic module consisting of electronic components which are disposed in vertically staggered layers (21, 22, 23) that are electro-conductively connected to each other by means of open areas (102) of contact peak points (12) or bond joints (10) inside the respective components and by strip conductors (83) which are connected to said open areas and arranged between the layers of the components. The invention also relates to a method for the production of an electronic module, either in a panel or in the form of individual components.

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IPC 8 full level

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Citation (search report)

See references of WO 03075347A2

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